Abstracts

Packaging and System Integration of Microwave and Digital Monolithic IC's

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Multilayer microwave substrates offer numerous advantages for today's high density packaging requirements. A single firing, multilayer process which uses a combination of thick and thin film metallization on hardened ceramic has been developed. This technology promotes the integration of digital, analog, and microwave circuit designs onto a single multilayer substrate. It provides an increase in interconnect density, a reduction in the number of parts and a decrease in assembly operations. This represents a novel packaging approach which provides greater design flexibility and superior electrical performance for microwave products such as couplers, filters, MMIC modules, delay lines, and millimeter-wave packages.

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